B-2800 BOARD SPECIFICATIONS

1. Board Layers: 14
2. Layer Stack Order:
   - Layer 1 (Artwork_1): Top comp layer (Signal_1) 1 oz, Zdiff=100 ohms
   - Layer 2 (Artwork_2): Power plane (AGND_A, AGND_B), 2oz
   - Layer 3 (Artwork_3): Inner Signal_3, 1 oz, Zdiff=100 ohms
   - Layer 4 (Artwork_11): Power plane (Ground), 2oz
   - Layer 5 (Artwork_4): Inner Signal_5, 1 oz, Zdiff=100 ohms
   - Layer 6 (Artwork_5): Power plane (PSV_A, PDV_B), 2oz.
   - Layer 7 (Artwork_6): Power plane (PI0V_A, PI0V_B, PI2V_A, PI2V_B), 2oz
   - Layer 8 (Artwork_7): Power plane (PI2V5_A, PI2V5_B, PI1V8A_A, PI1V8A_B), 2oz
   - Layer 9 (Artwork_8): Power plane (NSV_A, NSV_B), 2oz
   - Layer 10 (Artwork_9): Inner Signal_4, 1 oz, Zdiff=100 ohms
   - Layer 11 (Artwork_11): Power plane (Ground), 2oz
   - Layer 12 (Artwork_10): Inner Signal_6, 1 oz, Zdiff=100 ohms
   - Layer 13 (Artwork_11): Power plane (Ground), 2oz
   - Layer 14 (Artwork_12): Bottom comp layer (Signal_2) 1 oz, Zdiff=100 ohms

3. Apply silkscreen on Top component side:
   - Artwork_13: Top silkscreen.
   - Artwork_14: Bottom silkscreen.

4. Apply solder mask over bare copper on both side:
   - Artwork_15: Top solder mask
   - Artwork_16: Bottom solder mask

5. Material: FR4, TG > 170°C
6. Board thickness: 0.090" +/- 0.010".
7. Diff traces impedance of all signal layers should be controlled at 100 ohms +/-5%.
8. Diff trace/gap/trace laid out in 5/5/5 mils, can be adjusted by PCB makers for impedance control.
9. Minimum Trace/gap = 5/5 mils
10. Copper thickness for signal layers before plating is 1oz.
11. Copper thickness for all power layers is 2oz.
12. Board finish type: Immersion gold.
13. Solder masking for all bare copper
14. All dimensions are in inches unless otherwise noted.
15. Send back stack-up parameters and suggested trace/gap for impedance control for approval.
16. Send back gerber plots (pdf is acceptable) for approval.

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